LiPOLY®
SHIU LI TECHNOLOGY CO.,LTD

S-putty2-s

Thermal Conductive Putty

LiPOLY S-putty2-s is a one-part dispensable material with thermal conductivity 6.0W/m*K. High deformation can fill small air gaps perfectly to remove tolerance. It also can overcome overflow and drying problems to increase the thermal conductivity. S-putty2-s is a great alternative to thermal grease and ideally suited for dispensing using the dispensing robot.

FEATURES

/ Thermal conductivity:6.0 W/m*K
/ Bond line thickness:100-1500μm
/ Designed to remove manufacturing tolerances
/ Does not produce stress on delicate components
/ No vertical flow
/ Dispensable for serial manufacture
/ For any high compression and low stress application

TYPICAL APPLICATION

/ Between CPU and heat sink
/ Between a component and heat sink
/ High speed mass storage drives
/ Telecommunication hardware
/ Flat-panel displays
/ Set-top box
/ IP CAM

CONFIGURATIONS

/ Cartridges: 30ml, 55ml, 330ml
/ Bucket: 1kg, 25kg

PRESERVATION

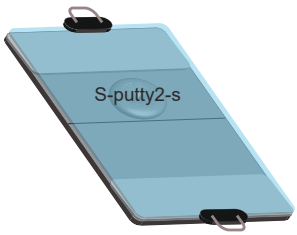
It can be preserved for 60 months under the condition of unopened and under room temperature 25℃.

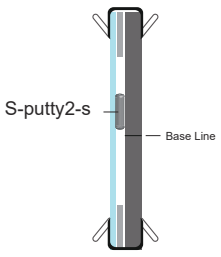
TYPICAL PROPERTIES

PROPERTY	S-putty2-s	TEST METHOD	UNIT
Color	Blue	Visual	-
Resin base	Silicone	-	-
Viscosity	3500	DIN 53018	Pa.s
Density	3.3	ASTM D792	g/cm³
Application temperature	-60~180	-	°C
Bond line thickness	100~1500	-	μm
Shelf life	60 months	-	-
ROHS & REACH	Compliant	-	-
ELECTRICAL			
Dielectric breakdown	12	ASTM D149	KV/mm
Volume resistivity	$>10^{13}$	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	6.0	ASTM D5470	W/m*K
Thermal impedance@10psi	0.062	ASTM D5470	°C-in²/ W
Thermal impedance@30psi	0.059	ASTM D5470	°C-in²/ W
Thermal impedance@50psi	0.053	ASTM D5470	°C-in²/ W

VERTICAL RELIABILITY

Using 1.5mm pad as a gap control, put the putty between the aluminum and the glass panel mark the initial position. Then, place it in the oven with 125℃ for 1,000 hours and observe its displacement after reliability test





Material no dropped or changed after high temperature aging testing